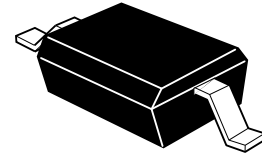

ZLLS410

10V Low leakage Schottky diode in SOD323

Summary

$V_R > 10V$; $I_F = 570mA$; I_R typ. $2\mu A$



Description

This compact SOD323 packaged 10 volt Schottky diode offers users an excellent performance combination, comprising high current operation, extremely low leakage and low forward voltage ensuring suitability for low voltage applications requiring efficient operation at higher temperatures above $85^{\circ}C$ - see safe operating area charts on page 5.

Features

- Extremely low leakage
- High current capability
- Low V_F , fast switching Schottky
- SOD323 package
- Package thermally rated to $150^{\circ}C$



Applications

- Low power DC-DC conversion
- Level shifting
- Reverse blocking

Ordering information

Device	Reel size (inches)	Tape width (mm)	Quantity per reel
ZLLS410TA	7	8	3000

Device marking

41

Absolute maximum ratings

Parameter	Symbol	Limit	Unit
Continuous reverse voltage	V_R	10	V
Forward current	I_F	570	mA
Peak repetitive forward current Rectangular pulse duty cycle 50%, Pulse width = 100 μ s	I_{FPK}	1.25	A
Non repetitive forward current $t \leq 100\mu$ s $t \leq 10$ ms	I_{FSM}	17 4	A
Power dissipation at $T_{amb} = 25^\circ\text{C}$			
Continuous	P_D	330	mW
$t \leq 5$ secs		390	mW
Operating and storage temperature range	T_j, T_{stg}	-55 to 150	$^\circ\text{C}$

Thermal resistance

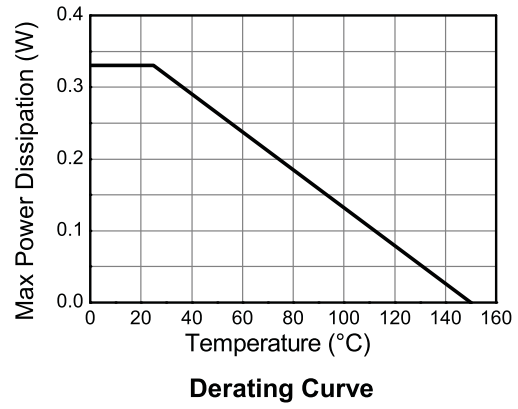
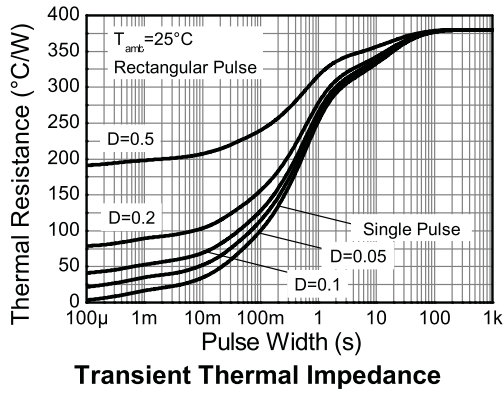
Parameter	Symbol	Limit	Unit
Junction to ambient ^(a)	$R_{\theta JA}$	379	$^\circ\text{C}/\text{W}$
Junction to ambient ^(b)	$R_{\theta JA}$	317	$^\circ\text{C}/\text{W}$

NOTES:

(a) For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

(b) For a device surface mounted on FR4 PCB measured at $t < 5$ secs.

Thermal characteristics



ZLLS410

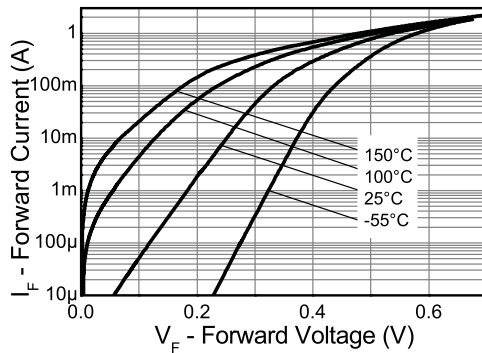
Electrical characteristics (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Reverse breakdown voltage	$BV_{(BR)R}$	10			V	$I_R = 200\mu\text{A}$
Forward voltage	V_F		250	290	mV	$I_F = 10\text{mA}^{(*)}$
			330	380	mV	$I_F = 100\text{mA}^{(*)}$
			535	580	mV	$I_F = 1\text{A}^{(*)}$
Reverse current	I_R		1.8	4	μA	$V_R = 5\text{V}$
			2.2	5	μA	$V_R = 8\text{V}$
			2.5	6	μA	$V_R = 10\text{V}$
			300	μA	$V_R = 8\text{V}, T_A = 85^{\circ}\text{C}$	
Diode capacitance	C_D		26		pF	$f = 1\text{MHz}, V_R = 10\text{V}$
Reverse recovery time	t_{rr}		3		ns	Switched from $I_F = 500\text{mA}$ to $V_R = 5.5\text{V}$ measured @ $I_R = 50\text{mA}$
Reverse recovery charge	Q_{rr}		210		pC	$di/dt = 500\text{mA/ns}$ $R_{source} = 6\Omega < R_{load} = 10\Omega$

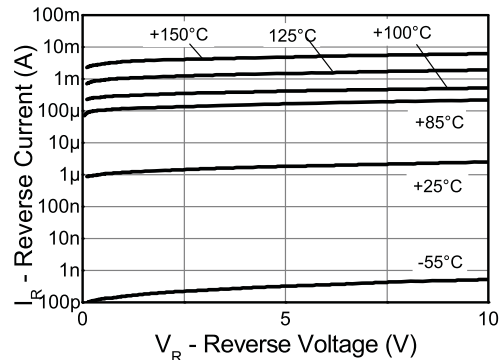
NOTES:

(*) Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

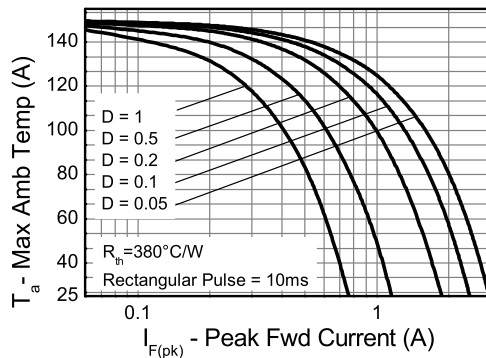
Typical characteristics



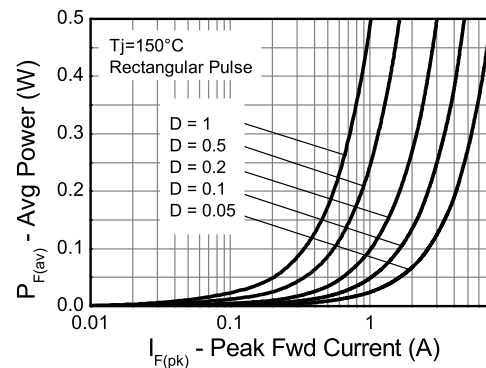
Typical Forward Characteristics



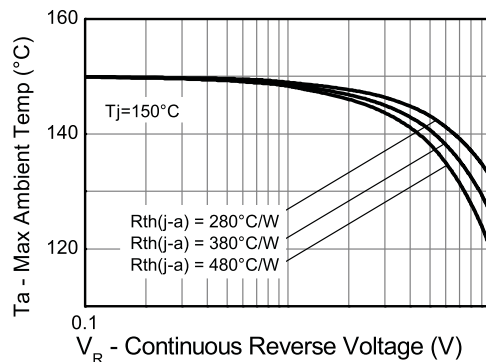
Typical Reverse Characteristics



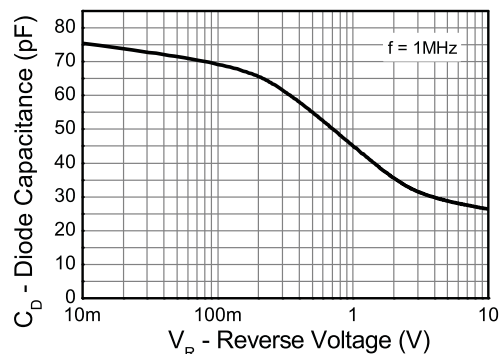
Typical Forward Safe Operating Area



Forward Power vs Peak Current



Typical Reverse Safe Operating Area



Capacitance vs Reverse Voltage

Note:

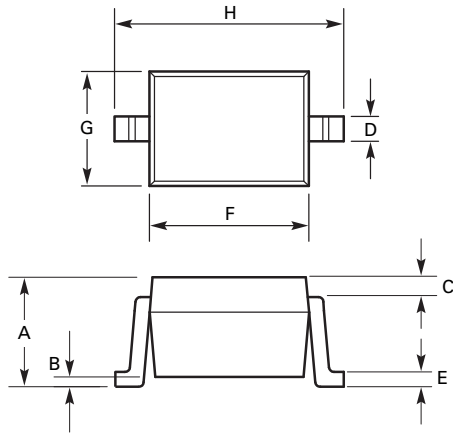
- Both forward and reverse dissipation contributes to junction temperature rise. Forward and reverse junction temperature rise are determined and added together to give total junction temperature rise.
- The safe operating curves are typical examples. Thermal resistance, pulse width and duty cycles are dependant on application.

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ZLLS410

Package outline - SOD323

Top mark



Cathode terminal is to RIGHT HAND side of part mark
Part marking text displayed is for example only

Dim.	Millimeters		Dim.	Millimeters	
	Min.	Max.		Min.	Max.
A	0.91	1.16	E	0.127	0.200
B	0.00	0.10	F	1.52	1.77
C	-	-	G	1.11	1.37
D	0.33	0.40	H	2.46	2.71

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"Obsolete"	Production has been discontinued

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Zetex sales offices

Europe	Americas	Asia Pacific	Corporate Headquarters
Zetex GmbH Kustermann-park Balansstraße 59 D-81541 München Germany Telefon: (49) 89 45 49 49 0 Fax: (49) 89 45 49 49 49 europe.sales@zetex.com	Zetex Inc 700 Veterans Memorial Highway Hauppauge, NY 11788 USA Telephone: (1) 631 360 2222 Fax: (1) 631 360 8222 usa.sales@zetex.com	Zetex (Asia Ltd) 3701-04 Metroplaza Tower 1 Hing Fong Road, Kwai Fong Hong Kong Telephone: (852) 26100 611 Fax: (852) 24250 494 asia.sales@zetex.com	Zetex Semiconductors plc Zetex Technology Park, Chadderton Oldham, OL9 9LL United Kingdom Telephone: (44) 161 622 4444 Fax: (44) 161 622 4446 hq@zetex.com

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